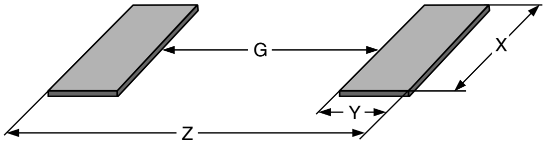
Vishay Draloric / Beyschlag Surface-Mount Resistors and Fuses

The given solder pad dimensions reflect the considerations for board design and assembly as outlined in publication IPC-7351 and the IEC 61188-6-2 standard.

The cited references specify design requirements for land pattern geometries for surface-mounted components with respect to the preparation of appropriate solder fillets. The given solder pad dimensions do not consider application specific requirements, e. g. suitable thermal resistance for sufficient heat dissipation or creepage and clearance distances between conductors at different potentials.

The given solder pad dimensions are recommended for the Vishay Draloric / Beyschlag SMD thin film chip and thin film / carbon film MELF resistors featured in the Vishay Draloric / Beyschlag SMD Resistors Selector Guide (www.vishay.com/doc?49252), as well as for the thin film chip fuses of the MFU Series (www.vishay.com/doc?28747) and the MFU AT Series (www.vishay.com/doc?28930), if not otherwise specified in the series datasheet.

RECOMMENDED SOLDER PAD DIMENSIONS FOR DRALORIC / BEYSCHLAG THIN FILM CHIP RESISTORS AND FUSES



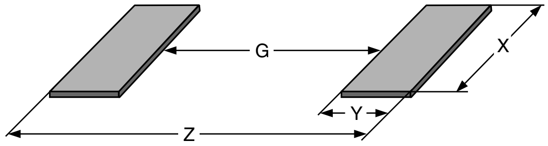
BASED ON IPC-7351, REFLOW SOLDERING				
SIZE	**G (mm)**	**Y (mm)**	**X (mm)**	**Z (mm)**
0201	0.27	0.43	0.42	1.13
0402	0.40	0.55	0.60	1.50
0406	0.40	0.55	1.70	1.50
0603	0.70	0.90	1.00	2.50
0612	0.70	0.90	3.30	2.50
0805	1.00	0.90	1.45	2.80
1206	1.75	1.15	1.80	4.05
1210	1.75	1.15	2.65	4.05

BASED ON IEC 61188-6-2, REFLOW SOLDERING				
SIZE	**G (mm)**	**Y (mm)**	**X (mm)**	**Z (mm)**
0201	0.30	0.24	0.32	0.78
0402	0.55	0.35	0.55	1.25
0406	0.55	0.35	1.55	1.25
0603	0.90	0.55	0.90	2.00
0612	0.90	0.55	3.15	2.00
0805	1.10	0.65	1.30	2.40
1206	2.10	0.80	1.65	3.70
1210	2.10	0.80	2.50	3.70

WAVE SOLDERING				
SIZE	**G (mm)**	**Y (mm)**	**X (mm)**	**Z (mm)**
0603	0.55	1.10	1.10	2.75
0805	0.80	1.25	1.50	3.30
1206	1.40	1.50	1.90	4.40
1210	1.40	1.50	2.50	4.40

For technical questions, contact: resistorstechsupport@ivishay.com

RECOMMENDED SOLDER PAD DIMENSIONS FOR DRALORIC / BEYSCHLAG THIN FILM / CARBON FILM MELF RESISTORS



BASED ON IPC-7351, REFLOW SOLDERING

SIZE	G (mm)	Y (mm)	X (mm)	Z (mm)
0102	0.95	1.05	1.25	3.05
0204	1.60	1.40	1.55	4.40
0207	3.20	1.80	2.40	6.80

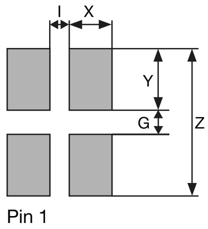
BASED ON IEC 61188-6-2, REFLOW SOLDERING

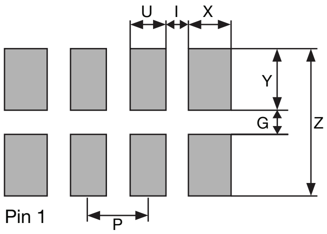
SIZE	G (mm)	Y (mm)	X (mm)	Z (mm)
0102	1.30	1.10	1.10	3.50
0204	1.90	1.70	1.40	5.30
0207	3.25	2.60	2.20	8.45

WAVE SOLDERING

SIZE	G (mm)	Y (mm)	X (mm)	Z (mm)
0102	0.70	1.20	1.50	3.10
0204	1.50	1.50	1.80	4.50
0207	2.80	2.10	2.60	7.00

RECOMMENDED SOLDER PAD DIMENSIONS FOR BEYSCHLAG THIN FILM CHIP ARRAYS





BASED ON IPC-7351, REFLOW SOLDERING

SIZE	G (mm)	Y (mm)	X (mm)	U (mm)	Z (mm)	I (mm)	P (mm)
0606	0.60	1.00	0.60	-	2.60	0.40	-
0612	0.60	1.00	0.60	0.40	2.60	0.40	0.80

BASED ON IEC 61188-6-2, REFLOW SOLDERING

SIZE	G (mm)	Y (mm)	X (mm)	U (mm)	Z (mm)	I (mm)	P (mm)
0606	0.60	0.70	0.65	-	2.00	0.35	-
0612	0.60	0.70	0.65	0.45	2.00	0.35	0.80